#### **GENERAL PURPOSE AMPLIFIER**

RoHS Compliant & Pb-Free Product
Package Style: SOT89

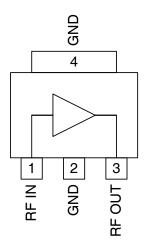


#### **Features**

- DC to >6000MHz Operation
- Internally Matched Input and Output
- 22dB Small Signal Gain
- +2.0dB Noise Figure
- +11dBm Output P1dB

#### **Applications**

- Basestation Applications
- Broadband, Low-Noise Gain Blocks
- IF or RF Buffer Amplifiers
- Driver Stage for Power Amplifiers
- Final PA for Low-Power Applications
- High Reliability Applications



Functional Block Diagram

#### **Product Description**

The RF3376 is a general purpose, low-cost RF amplifier IC. The device is manufactured on an advanced Gallium Arsenide Heterojunction Bipolar Transistor (HBT) process, and has been designed for use as an easily-cascadable  $50\Omega$  gain block. Applications include IF and RF amplification in wireless voice and data communication products operating in frequency bands up to 6000 MHz. The device is self-contained with  $50\Omega$  input and output impedances and requires only two external DC-biasing elements to operate as specified.

#### **Ordering Information**

RF3376 General Purpose Amplifier
RF3376PCBA-410 Fully Assembled Evaluation Board

#### **Optimum Technology Matching® Applied**

<b>▼</b> GaAs HBT	☐ SiGe BiCMOS	☐ GaAs pHEMT	☐ GaN HEMT
☐ GaAs MESFET	☐ Si BiCMOS	☐ Si CMOS	
☐ InGaP HBT	☐ SiGe HBT	☐ Si BJT	



#### **Absolute Maximum Ratings**

Parameter	Rating	Unit
Input RF Power	+3	dBm
Operating Ambient Temperature	-40 to +85	°C
Storage Temperature	-60 to +150	°C
Icc	40	mA



#### Caution! ESD sensitive device.

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical performance or functional operation of the device under Absolute Maximum Rating conditions is not implied.

RoHS status based on EU Directive 2002/95/EC (at time of this document revision).

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Parameter	Specification		Unit	Condition	
raidilletei	Min.	Тур.	Max.	Onit	Condition
Overall					T=25 °C, I <sub>CC</sub> =35 mA (See Note 1.)
Frequency Range		DC to >6000		MHz	
3dB Bandwidth		2		GHz	
Gain	22.0	23.5		dB	Freq=500MHz
	21.0	22.5		dB	Freq=1000MHz
	18.0	19.8		dB	Freq=2000MHz
		18.0		dB	Freq=3000MHz
		16.0			Freq=4000MHz
		12.8			Freq=6000MHz
Noise Figure		2.0		dB	Freq=2000MHz
Input VSWR		<2:1			In a $50\Omega$ system, DC to $4500 \text{MHz}$
Output VSWR		<2:1			In a $50\Omega$ system, DC to $6000\text{MHz}$
Output IP <sub>3</sub>	+22.0	+24.4		dBm	Freq=1000MHz
	+21.5	+23.4		dBm	Freq=2000MHz
Output P <sub>1dB</sub>	+9.5	+11.5		dBm	Freq=1000MHz
	+9.5	+11.5		dBm	Freq=2000MHz
Reverse Isolation		22.5		dB	Freq=2000MHz
Thermal					I <sub>CC</sub> =35mA, P <sub>DISS</sub> =110mW. (See Note 3.)
Theta <sub>JC</sub>		216		°C/W	
Maximum Measured Junction Temperature at DC Bias Conditions		109		°C	T <sub>CASE</sub> =+85°C
Mean Time To Failures		35000		years	T <sub>CASE</sub> =+85°C
Power Supply					With $22\Omega$ bias resistor
Device Operating Voltage		3.4	3.5	V	At pin 8 with I <sub>CC</sub> =35mA
		4.2	4.5	V	At evaluation board connector, I <sub>CC</sub> =35mA
Operating Current		35	40	mA	See Note 2.

Note 1: All specification and characterization data has been gathered on standard FR-4 evaluation boards. These evaluation boards are not optimized for frequencies above 2.5 GHz. Performance above 2.5 GHz may improve if a high performance PCB is used.

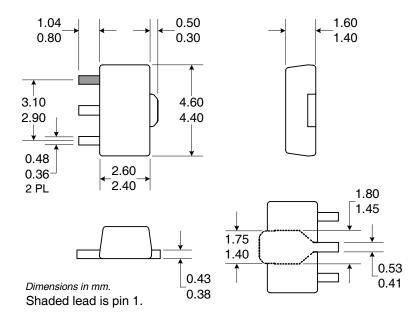
Note 2: The RF3376 must be operated at or below 40 mA in order to achieve the thermal performance listed above. While the RF3376 may be operated at higher bias currents, 35 mA is the recommended bias to ensure the highest possible reliability and electrical performance.

Note 3: Because of process variations from part to part, the current resulting from a fixed bias voltage will vary. As a result, caution should be used in designing fixed voltage bias circuits to ensure the worst case bias current does not exceed 40 mA over all intended operating conditions.



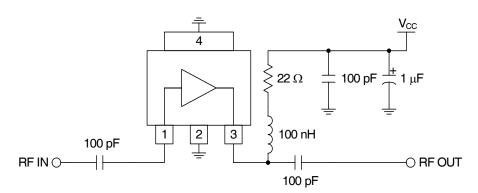
Pin	Function	Description	Interface Schematic
1	RF IN	RF input pin. This pin is NOT internally DC blocked. A DC blocking capacitor, suitable for the frequency of operation, should be used in most applications. DC coupling of the input is not allowed, because this will override the internal feedback loop and cause temperature instability.	
2	GND	Ground connection.	
3	RF OUT	RF output and bias pin. Biasing is accomplished with an external series resistor and choke inductor to $V_{CC}$ . The resistor is selected to set the DC current into this pin to a desired level. The resistor value is determined by the following equation: $R = \frac{(V_{SUPPLY} - V_{DEVICE})}{I_{CC}}$ Care should also be taken in the resistor selection to <b>ensure that the current into the part never exceeds 40 mA over the planned operating temperature.</b> This means that a resistor between the supply and this pin is always required, even if a supply near 3.4V is available, to provide DC feedback to prevent thermal runaway. Because DC is present on this pin, a DC blocking capacitor, suitable for the frequency of operation, should be used in most applications. The supply side of the bias network should also be well bypassed.	RF INO ET
4	GND	Ground connection.	

## **Package Drawing**



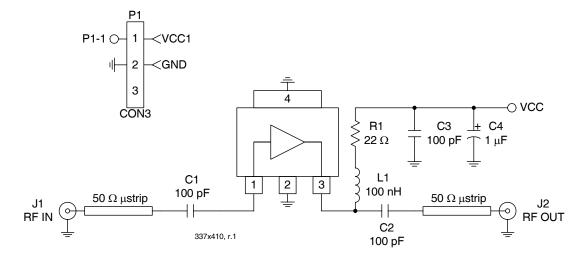


## **Application Schematic**



#### **Evaluation Board Schematic**

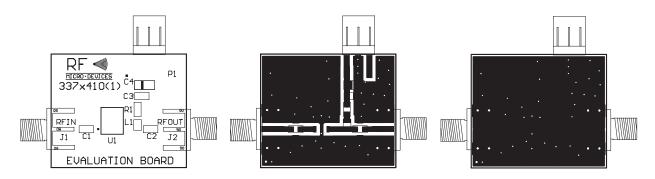
(Download Bill of Materials from www.rfmd.com.)



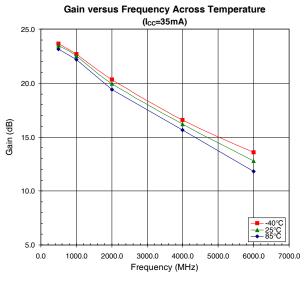


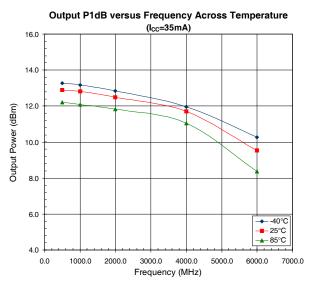
# Evaluation Board Layout Board Size 1.195" x 1.000"

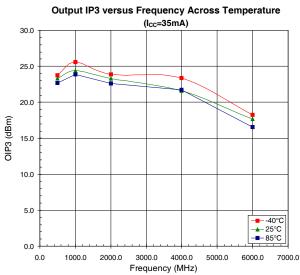
**Board Thickness 0.033", Board Material FR-4** 

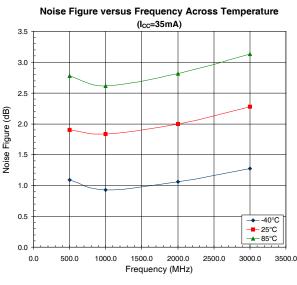


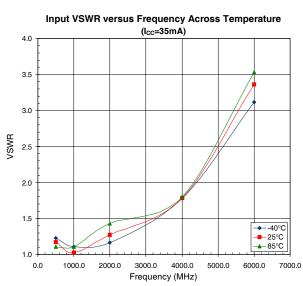


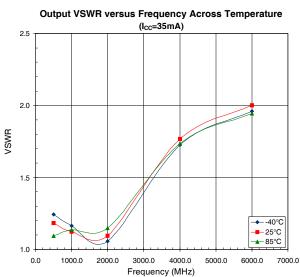




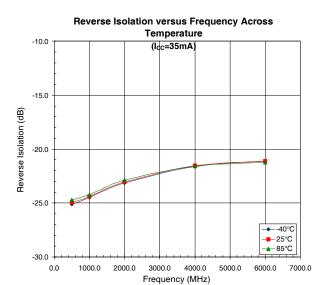


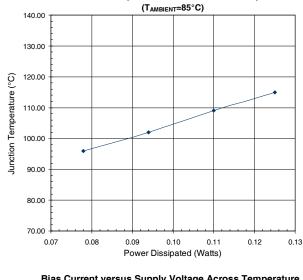












**Junction Temperature versus Power Dissipated** 

